

N-Channel Enhancement Mode Power MOSFET

Description

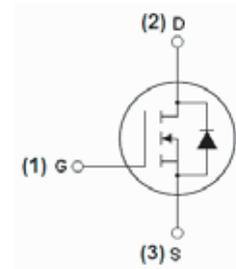
The RM115N65T2 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Feature

- $V_{DS} = 65V, I_D = 115A$
 $R_{DS(ON)} < 4.7m\Omega @ V_{GS}=10V$
 $R_{DS(ON)} < 8.0m\Omega @ V_{GS}=4.5V$
- Special process technology for high ESD capability
- High density cell design for ultra low R_{dson}
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Halogen-free



Schematic diagram



TO-220-3L top view

100% UIS TESTED!
100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
115N65	RM115N65T2	TO-220-3L	-	-	-

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	65	V
Gate-Source Voltage	V_{GS}	+20/-12	V
Drain Current-Continuous	I_D	115	A
Drain Current-Continuous($T_C=100^\circ C$)	$I_D(100^\circ C)$	72	A
Pulsed Drain Current	I_{DM}	460	A

Maximum Power Dissipation	P_D	160	W
Derating factor		1.28	W/°C
Single pulse avalanche energy ^(Note 5)	E_{AS}	174	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta Jc}$	0.78	°C/W
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Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

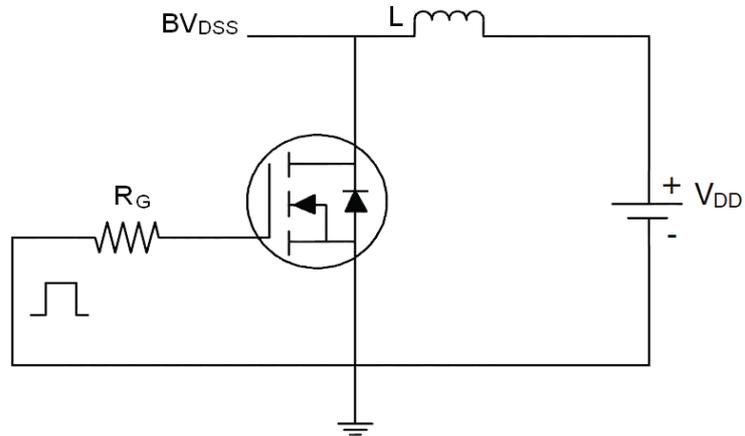
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	65	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.5	2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=15A$	-	3.9	4.7	m Ω
		$V_{GS}=4.5V, I_D=8A$	-	6.2	8.0	
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=3A$	-	12	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V,$ $F=1.0\text{MHz}$	-	2940	5900	PF
Output Capacitance	C_{oss}		-	850	1700	PF
Reverse Transfer Capacitance	C_{rss}		-	15	30	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V, I_D=1A$ $V_{GS}=10V, R_{GEN}=6\Omega$	-	10.6	21	nS
Turn-on Rise Time	t_r		-	16.5	33	nS
Turn-Off Delay Time	$t_{d(off)}$		-	48	96	nS
Turn-Off Fall Time	t_f		-	78	150	nS
Total Gate Charge	Q_g	$V_{DS}=48V, I_D=5A,$ $V_{GS}=10V$	-	54	108	nC
Gate-Source Charge	Q_{gs}		-	5.2	10.4	nC
Gate-Drain Charge	Q_{gd}		-	16.1	32.2	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{GS}=0V, I_S=20A$	-	-	1.0	V
Diode Forward Current ^(Note 2)	I_S	-	-	-	115	A

Notes:

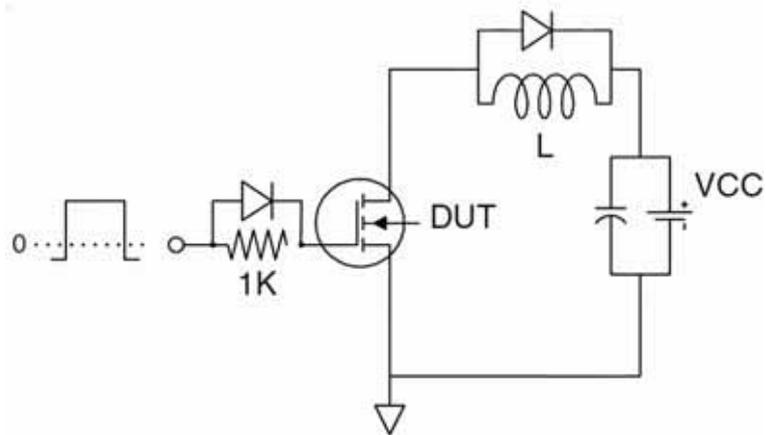
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_J=25^\circ\text{C}, V_{DD}=30V, V_{GS}=10V, L=0.5\text{mH}, R_g=25\Omega$

Test circuit

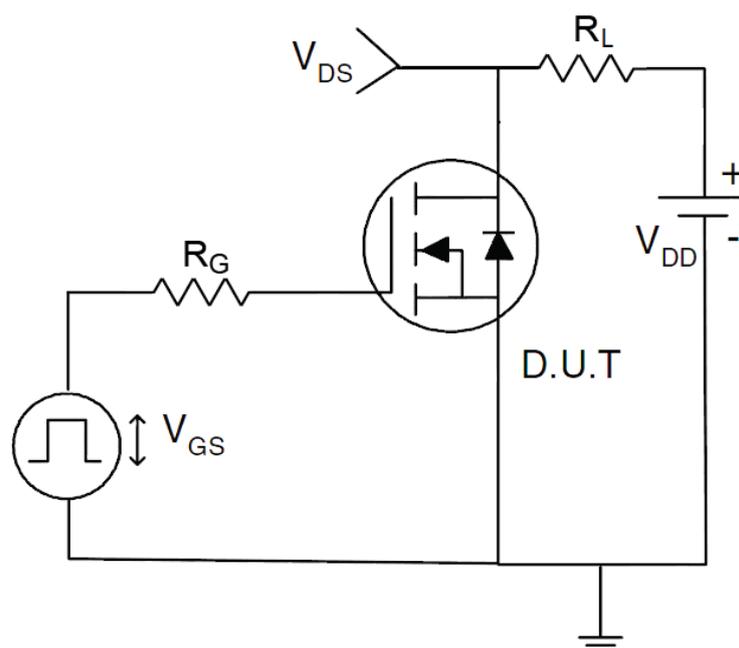
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:



RATING AND CHARACTERISTICS CURVES (RM115N65T2)

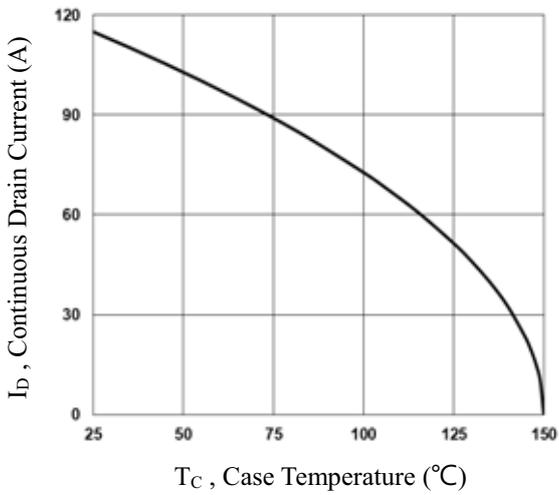


Fig.1 Continuous Drain Current vs. T_c

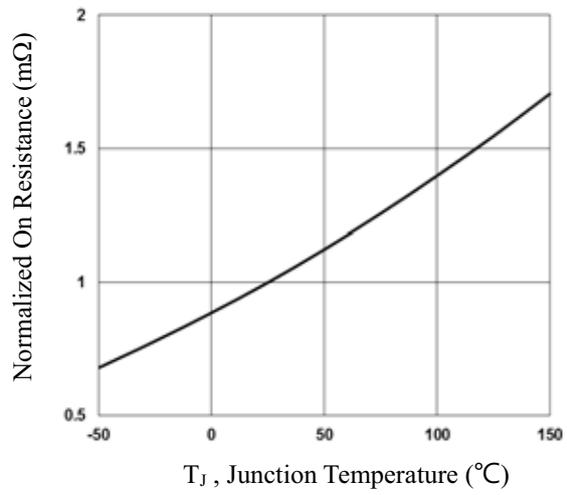


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

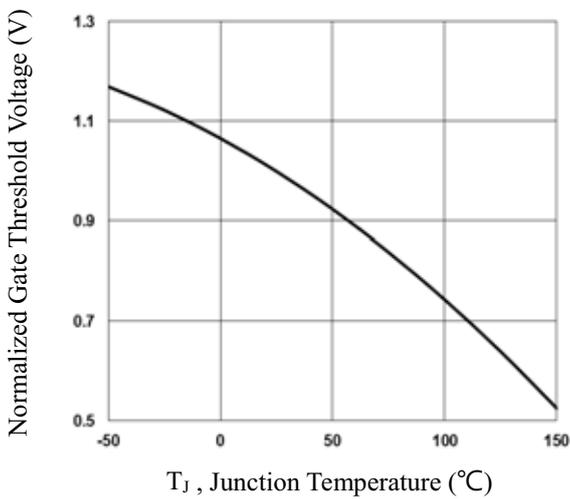


Fig.3 Normalized V_{th} vs. T_j

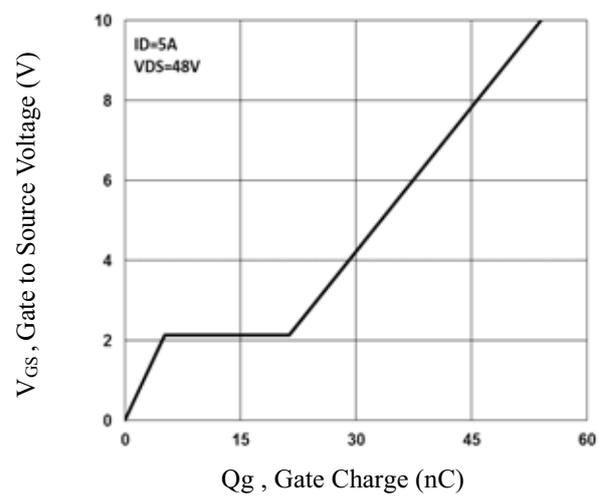


Fig.4 Gate Charge Characteristics

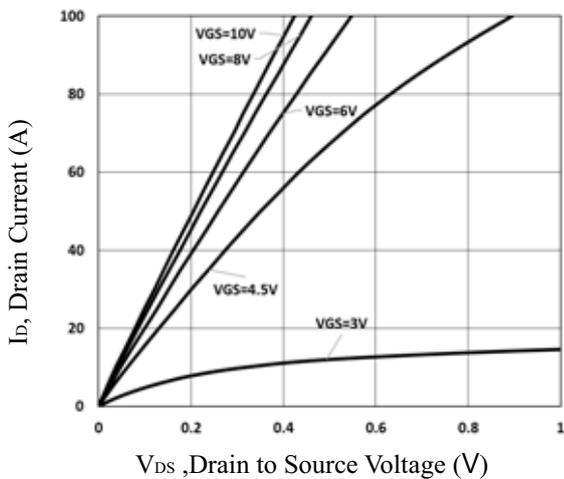


Fig.5 Typical Output Characteristics

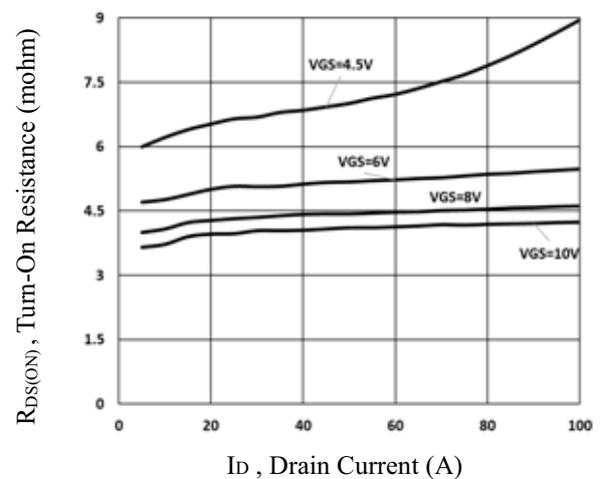


Fig.6 Turn-On Resistance vs. I_D

RATING AND CHARACTERISTICS CURVES (RM115N65T2)

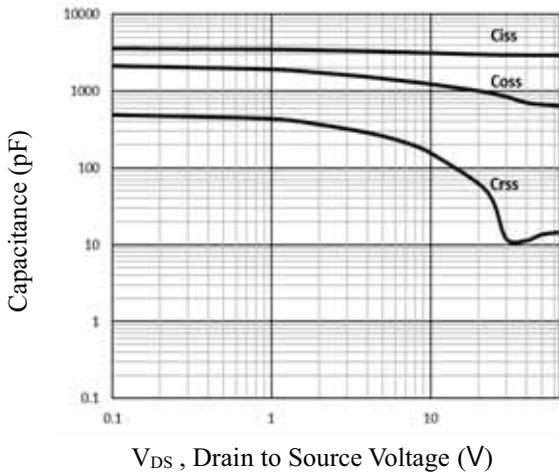


Fig.7 Capacitance Characteristics

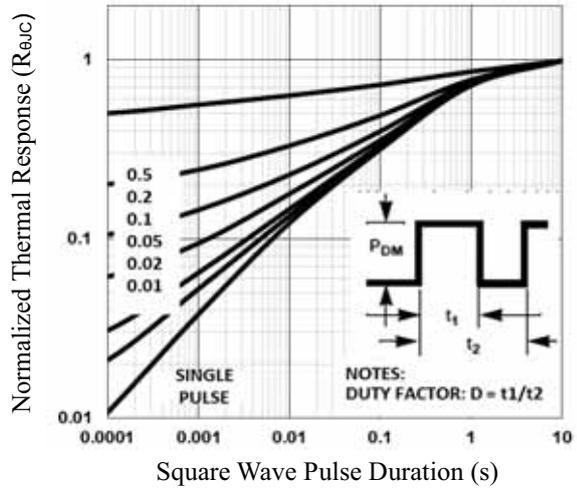


Fig.8 Normalized Transient Impedance

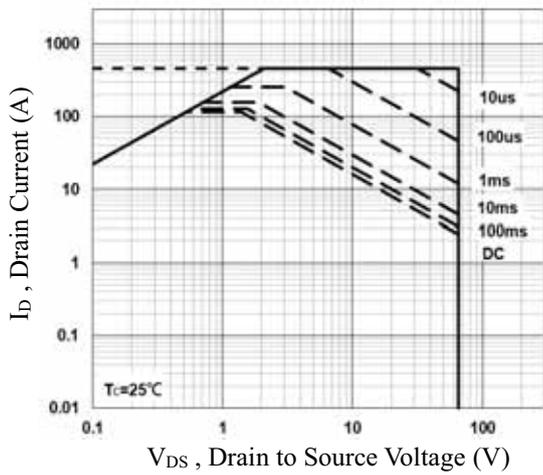


Fig.9 Maximum Safe Operation Area

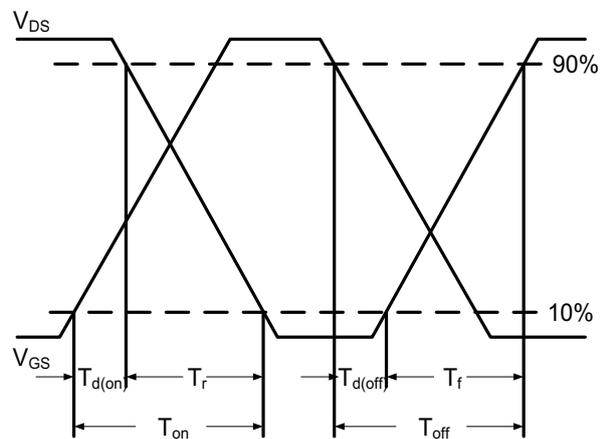


Fig.10 Switching Time Waveform

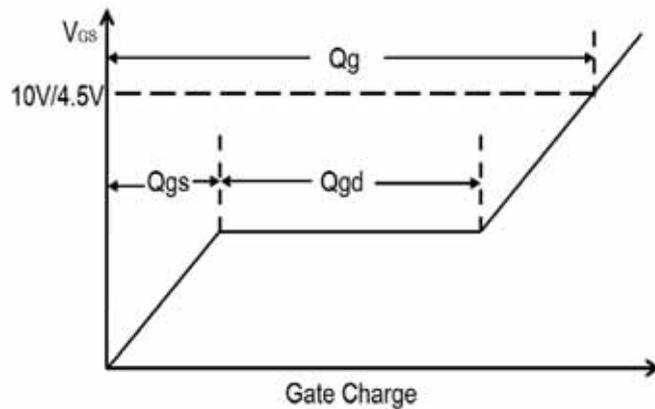
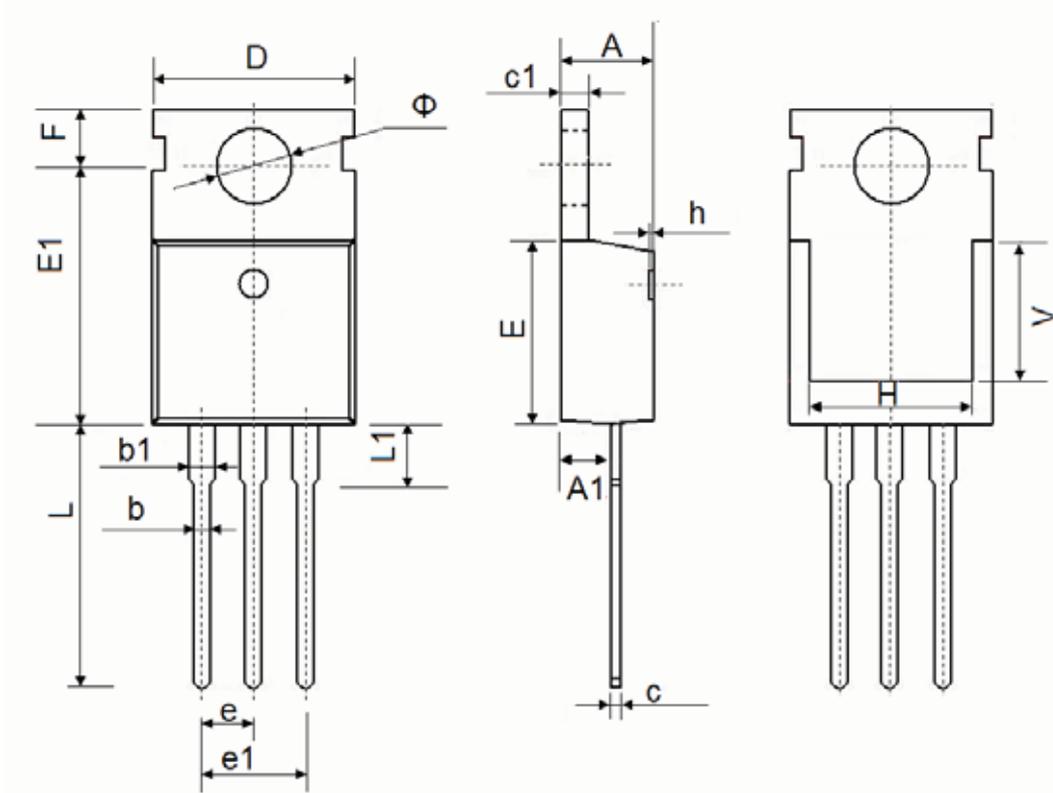


Fig.11 Gate Charge Waveform

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150

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